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(71) Applicant: **DECA TECHNOLOGIES, INC.** [US/US]; 7855 S. River Parkway STE 111, Tempe, Arizona 85284 (US).

(72) Inventor; and
(71) Applicant : **SCANLAN, Christopher** [US/US]; 350 W Yellowstone Way, Chandler, Arizona 85248 (US).

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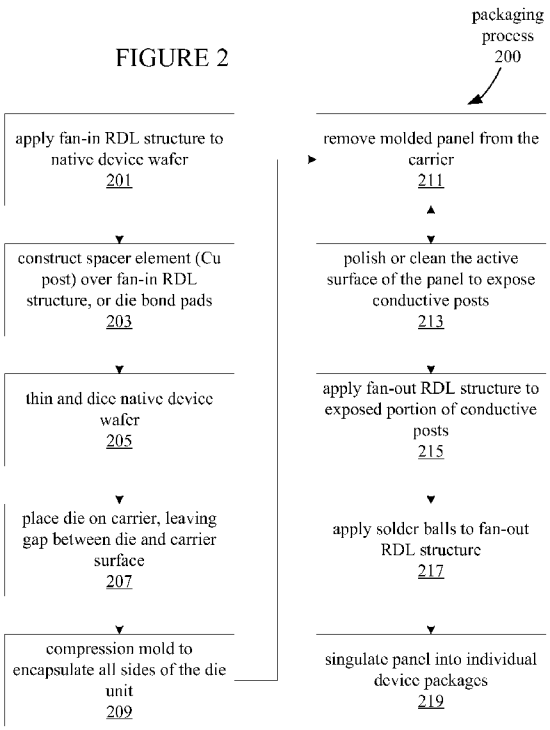
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[Continued on next page]

(54) Title: FULLY MOLDED FAN-OUT

(57) Abstract: A method for manufacturing a device package may include constructing a spacer element coupled with a surface of a semiconductor die unit, where the spacer element is configured to create a gap between the semiconductor die unit and a surface of a carrier, and encapsulating the semiconductor die unit within a mold compound, where the encapsulating includes introducing the mold compound into the gap.

FIGURE 2



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